

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT										
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT										
<b>CONVEYING PARTY DATA</b>											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jingang Wu</td> <td>06/22/2007</td> </tr> <tr> <td>Fei Luo</td> <td>06/22/2007</td> </tr> <tr> <td>Guanqie Gao</td> <td>06/22/2007</td> </tr> <tr> <td>Cheng Yang</td> <td>06/22/2007</td> </tr> </tbody> </table>		Name	Execution Date	Jingang Wu	06/22/2007	Fei Luo	06/22/2007	Guanqie Gao	06/22/2007	Cheng Yang	06/22/2007
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<b>RECEIVING PARTY DATA</b>											
<b>Name:</b>	Semiconductor Manufacturing International (Shanghai) Corporation										
<b>Street Address:</b>	18 Zhang Jiang Road, Pudong New Area										
<b>City:</b>	Shanghai										
<b>State/Country:</b>	CHINA										
<b>Postal Code:</b>	201203										
<b>PROPERTY NUMBERS Total: 1</b>											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11615972</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11615972						
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Application Number:	11615972										
<b>CORRESPONDENCE DATA</b>											
<b>Fax Number:</b>	(415)576-0300										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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<b>Address Line 1:</b>	Two Embarcadero Center, Eighth Floor										
<b>Address Line 4:</b>	San Francisco, CALIFORNIA 94111-3834										
<b>ATTORNEY DOCKET NUMBER:</b>	021653-0240000US										
<b>NAME OF SUBMITTER:</b>	Richard T. Ogawa										
Total Attachments: 2 source=021653-024000US Assignment#page1.tif											

**CH \$40.00 11615972**



Attorney Docket No.: 021653-024000US  
 Client Reference No.: I-05-690

**ASSIGNMENT OF PATENT APPLICATION**

JOINT

WHEREAS, **Jingang Wu** of 18 Zhang Jiang Rd. Pudong New Area, Shanghai, 201203 People's Republic of China; **Fei Luo** of 18 Zhang Jiang Rd. Pudong New Area, Shanghai, 201203 People's Republic of China; **Guanqie Guo** of 18 Zhang Jiang Rd. Pudong New Area, Shanghai, 201203 People's Republic of China; and **Cheng Yang** of 18 Zhang Jiang Rd. Pudong New Area, Shanghai, 201203 People's Republic of China, hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: **SYSTEM AND METHOD FOR DIRECT ETCHING**  
 Filing Date: **December 23, 2006**  
 Application No.: **11/615,972; and**

WHEREAS, **Semiconductor Manufacturing International (Shanghai) Corporation**, a corporation of People's Republic of China, located at 18 Zhang Jiang Rd., Pudong New Area, Shanghai, 201203 People's Republic of China, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignors hereby authorize and request Townsend and Townsend and Crew LLP, Two Embarcadero Center, Eighth Floor, San Francisco, CA 94111-3834, to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated: 2007/6/22

Jingang Wu  
 Jingang Wu

Dated: 2007/06/22

Fei Luo  
 Fei Luo

Assignment

Attorney Docket No.: 021653-024000US

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Dated: 2007/06/22

Guanqie Gao  
Guanqie Gao

Dated: 2007/06/22

Cheng Yang  
Cheng Yang

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